

# ANGI044050-P50

### **C-band matched GaN Device**

#### **Features:**

Frequency: 4.4~5GHz

Saturated Output Power: Psat≥50dBm

PowerGain: Gain≥10dB Add-Efficiency: PAE≥45% Port Matching: Zin/Zout=50Ω

## **Description:**

ANGI044050-P50 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 4.4~5GHz. This device can be used in different RF/Microwave system and subsystem.

The high output power level, high efficiency and wide operating temperature range can make application very flexible.

# Maximun Ratings (TC=25°C, Not recommended working under this condition):

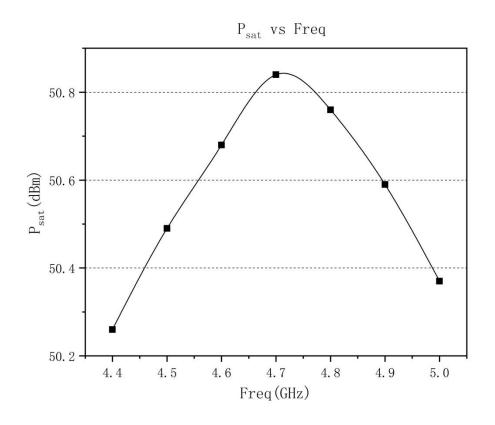
	Symbol	Value	Unit
Voltage between source and drain	<b>V</b> DS	40	V
Voltage between gate and source	V <sub>G</sub> s	-5	V
Storage Temperature Range	$T_{stg}$	-65 to +175	°C
Drain and Source Channel Temperature	Tch	175	°C



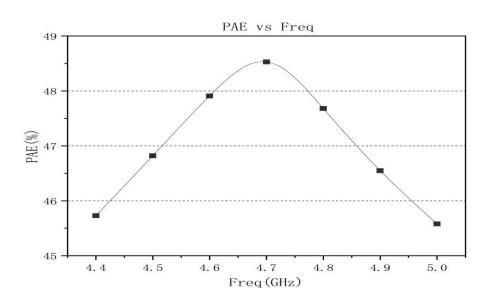
## **Electrical Characteristics:**

				Value		
	Symbol	Test condition	Min	Тур	Max	Unit
Drain Current	ldsr	Vds=28V CW. Pin: 40dBm Freq: 4.4~5GHz	-	7	-	А
Saturated Output Power	Psat		50	-	-	dBm
Gain	Gp		10	-	-	dB
Add-Efficiency	PAE		45	-	-	%
Gain Flatness	ΔG		-0.8	-	+0.8	dB

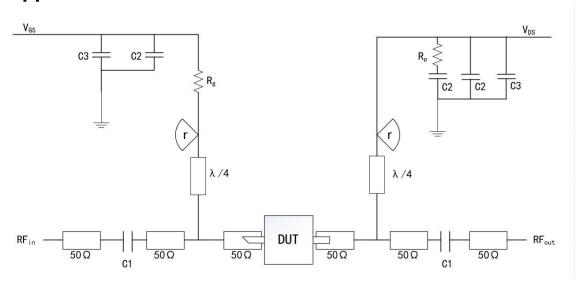
# **Typical Curve:**



## **Internal Matching GaN Device**



## **Application Circuit:**



DUT: Device to be tested

C1:4.7pF  $R_p$ :51 $\Omega$ 

C2:1000pF  $R_G:15\Omega$ 

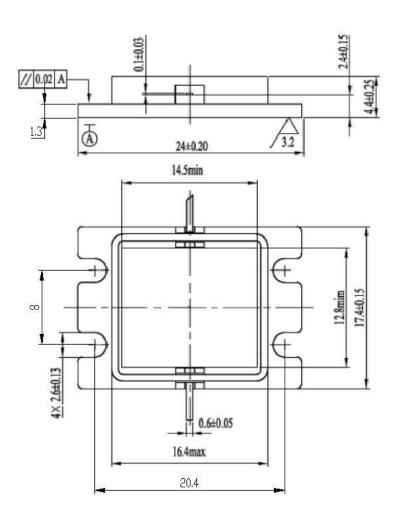
C3:100uF r(radius)≈5.8mm(Rogers5880, 20mil)



#### **ESD Level:**

ESD	Class III	2000V

## **Outline:**



### **Precautions for use:**

- Pay attention to drying transportation and storage.
- Pay attention to anti-static during chip use and assembly, and wear grounding anti-static bracelet.
- When powering up, first apply grid power then add leakage.